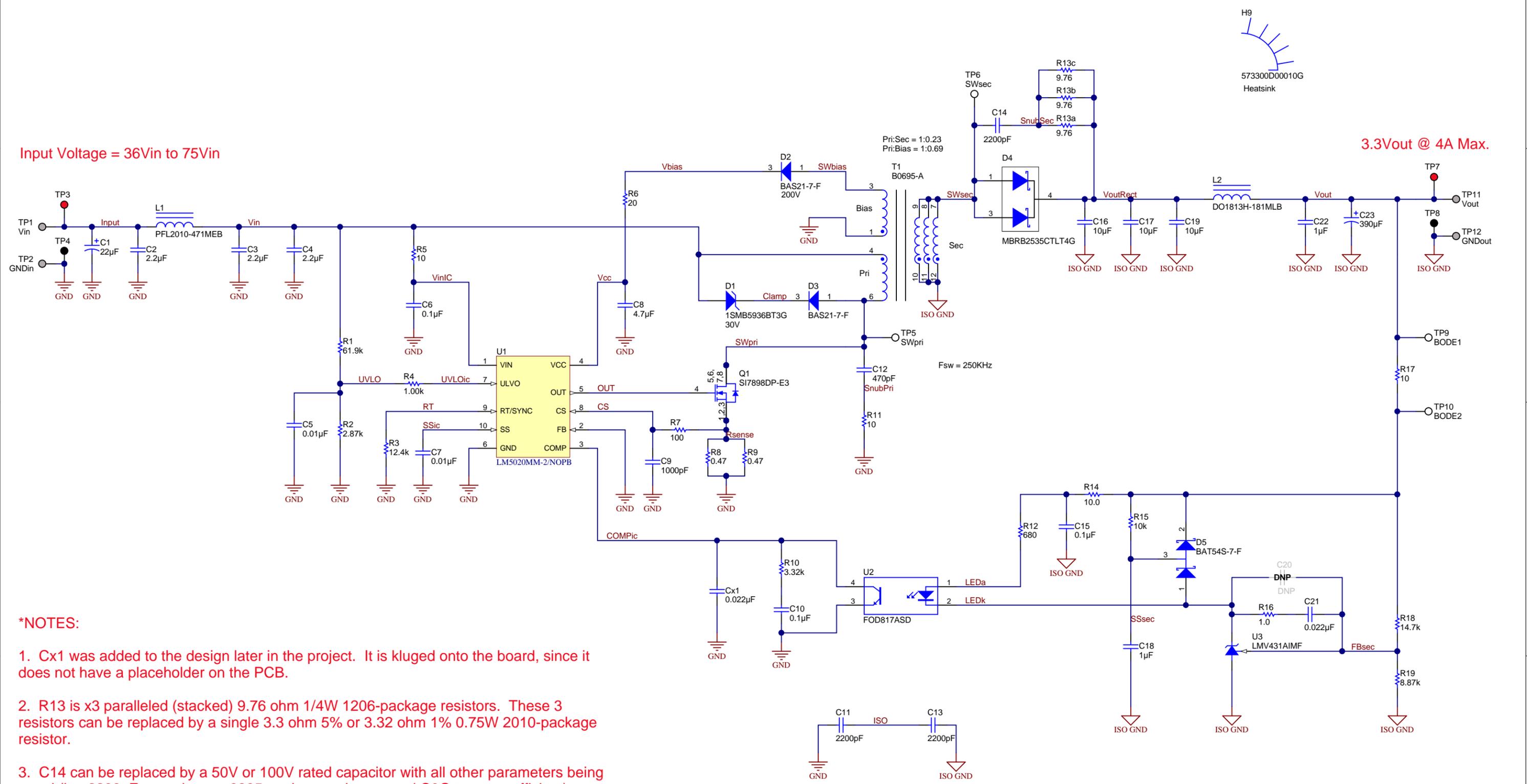


Input Voltage = 36Vin to 75Vin

3.3Vout @ 4A Max.



***NOTES:**

1. Cx1 was added to the design later in the project. It is kluged onto the board, since it does not have a placeholder on the PCB.
2. R13 is x3 paralleled (stacked) 9.76 ohm 1/4W 1206-package resistors. These 3 resistors can be replaced by a single 3.3 ohm 5% or 3.32 ohm 1% 0.75W 2010-package resistor.
3. C14 can be replaced by a 50V or 100V rated capacitor with all other parameters being equal (i.e. 2200pF capacitance, 0805-package or larger, and C0G temp. coefficient).

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Designed for: Public Release		Mod. Date: 3/9/2017	
Project Title: LM5020-2 Isolated Flyback Converter			
Sheet Title:			
Number: PMP10632		Rev: A	
SVN Rev: Version control disabled			
Drawn By:		Assembly Variant: 001	
Engineer: H Kasparian/B Sheehan		File: PMP10632 RevA2 Schematic.SchDoc	
		Sheet: 1 of 2	
		Size: B	
		Contact: http://www.ti.com/support	



H2 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH H6 NY PMS 440 0025 PH H8 NY PMS 440 0025 PH

H1 1902C H3 1902C H5 1902C H7 1902C

FID1 FID2 FID3

PCB Number: PMP10632
PCB Rev: A

PCB
LOGO
Texas Instruments

PCB
LOGO
FCC disclaimer

Label Table

Variant	Label Text
001	

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: PMP10632		Rev: A	Designed for: Public Release	Mod. Date: 4/23/2015
SVN Rev: Version control disabled		Project Title: LM5020-2 Isolated Flyback Converter		
Drawn By:		Assembly Variant: 001	Sheet: 2 of 2	
Engineer: H Kasparian/B Sheehan		File: PMP10632_Hardware_ANSI-B.SchDoc	Size: B	http://www.ti.com
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